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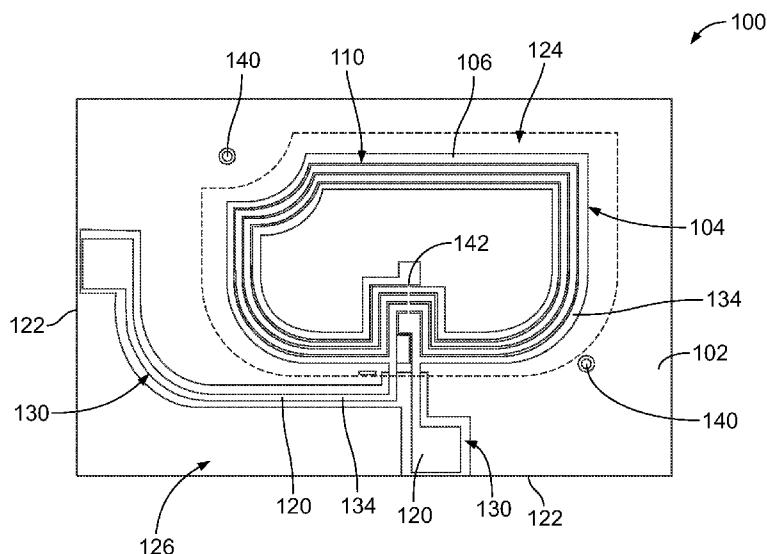


FIG. 2

(57) Abstract: An electrical component (100) including a substrate (102) having a circuit area (124) and a sacrificial area (126). A lift-off layer (130) is deposited on the substrate in the sacrificial area. A seed layer is deposited on the substrate in the circuit area and on the lift-off layer in the sacrificial area. A plating layer (134) is electrodeposited on the seed layer. The plating layer forms a circuit (104) in the circuit area. The plating layer forms plating electrodes (120) in the sacrificial area. The lift-off layer is removable from the substrate. The seed layer and the plating layer on the lift-off layer are removed with the lift-off layer when the lift-off layer is removed from the substrate, leaving the circuit on the substrate.